

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

Claims 1-70 (Canceled)

Claim 71 (Currently amended): A method of planarizing ~~a plurality of~~ probes, wherein said probes are disposed to correspond to ~~a plurality of~~ terminals of one or more devices to be tested and ~~subsets of~~ said probes are disposed on ~~each of a~~ plurality of ~~probe~~ substrates, said method comprising:

adjusting a planarity of contact portions of said probes to correspond to a planarity of said terminals, wherein said step of adjusting comprises:

adjusting a shape of a surface of a first of said ~~probe~~ substrates, wherein ~~one a~~ first plurality of said ~~subsets of~~ probes is attached to said surface of said first ~~probe~~ substrate; and

adjusting a shape of a surface of a second of said ~~probe~~ substrates, wherein ~~another a second plurality~~ of said ~~subsets of~~ probes is attached to said surface of said second ~~probe~~ substrate.

Claim 72 (Currently amended): The method of claim 71, wherein said step of adjusting a shape of a surface of said first ~~probe~~ substrate comprises selectively applying one of a push or a pull force to a first region of said first ~~probe~~ substrate.

Claim 73 (Currently amended): The method of claim 71, wherein said step of adjusting a shape of a surface of said first ~~probe~~ substrate further comprises:

applying a pull force to a first region of said ~~probe~~ first substrate, and
applying a push force to a second region of said ~~probe~~ first substrate.

Claim 74 (Currently amended): The method of claim 73, wherein:

said first region corresponds to a central region of said surface of said first ~~probe~~ substrate,

said second region corresponds to a peripheral region of said surface of said first ~~probe~~ substrate.

Claim 75 (Currently amended): The method of claim 71, wherein said step of adjusting a shape of a surface of said first ~~probe~~ substrate further comprises applying a plurality of forces to a plurality of regions of said first ~~probe~~ substrate.

Claim 76 (New): The method of claim 71, wherein said step of adjusting a shape of a surface of a first of said substrates comprises adjusting said shape without contacting said one or more devices to be tested.

Claim 77 (New): The method of claim 76, wherein said step of adjusting a shape of a surface of a second of said substrates comprises adjusting said shape without contacting said one or more devices to be tested.

Claim 78 (New): The method of claim 71, wherein said step of adjusting a shape of a surface of a first of said substrates comprises activating an actuator configured to impart a selected one of a push force or a pull force to said first substrate.

Claim 79 (New): The method of claim 78, wherein said step of adjusting a shape of a surface of a second of said substrates comprises activating an actuator configured to impart a selected one of a push force or a pull force to said second substrate.

Claim 80 (New): The method of claim 71, wherein said step of adjusting a shape of a surface of a first of said substrates comprises selectively activating a plurality of first actuators, each said first actuator configured to impart a push or a pull force to a different region of said first substrate.

Claim 81 (New): The method of claim 80, wherein at least one of said first actuators is configured to impart a selected one of a push or a pull force to said first substrate, and at least another of said first actuators is configured to impart only a push force to said first substrate.

Claim 82 (New): The method of claim 81, wherein said step of adjusting a shape of a surface of a second of said substrates comprises selectively adjusting a plurality of second actuators, each said second actuator configured to impart a push or a pull force to a different region of said second substrate.

Claim 83 (New): The method of claim 82, wherein at least one of said second actuators is configured to impart a selected one of a push or a pull force to said second substrate, and at least another of said second actuators is configured to impart only a push force to said second substrate.

Claim 84 (New): The method of claim 80, wherein said step of adjusting a shape of a surface of a second of said substrates comprises selectively activating a plurality of second actuators, each said second actuator configured to impart a push or a pull force to a different region of said second substrate.

Claim 85 (New): The method of claim 71, wherein said first plurality of probes comprises a first array of probes.

Claim 86 (New): The method of claim 85, wherein said second plurality of probes comprises a second array of probes.

Claim 87 (New): The method of claim 71, wherein each said probe of said first plurality of probes is elongate and resilient, whereby each said probe of said first plurality of probes provides individual compliance with respect to said terminals of said device to be tested and said step of adjusting a shape of said first of said substrates provides global planarization of said first plurality of probes with respect to said terminals of said device to be tested.

Claim 88 (New): The method of claim 87, wherein each said probe of said second plurality of probes is elongate and resilient, whereby each said probe of said second plurality of probes provides individual compliance with respect to said terminals of said device to be tested and said step of adjusting a shape of said second of said substrates provides global planarization of said second plurality of probes with respect to said terminals of said device to be tested.

Claim 89 (New): A method of testing an electronic device, said method comprising:
 providing a probe card assembly, said probe card assembly comprising a plurality of substrates and a plurality of probes disposed on each said substrate;
 adjusting a planarity of contact portions of said probes by adjusting a shape of each of said substrates;
 thereafter bringing said contact portions of said probes and terminals of said electronic device into contact; and
 testing said electronic device.

Claim 90 (New): The method of claim 89, wherein said electronic device comprises a die of an unsingulated semiconductor wafer.

Claim 91 (New): The method of claim 90, wherein said electronic device comprises a plurality of dies of an unsingulated semiconductor wafer.

Claim 92 (New): The method of claim 90 further comprising singulating said die from said wafer.

Claim 93 (New): The method of claim 89, wherein said step of adjusting comprises selectively applying one of a push or a pull force to a first region of each of said substrates.

Claim 94 (New): The method of claim 89, wherein said step of adjusting comprises:
 applying a pull force to a first region of each of said substrates, and
 applying a push force to a second region of each of said substrates.

Claim 95 (New): The method of claim 94, wherein:

said first region corresponds to a central region of each of said substrates,
said second region corresponds to a peripheral region of each of said substrates.

Claim 96 (New): The method of claim 89, wherein said step of adjusting comprises applying a plurality of forces to a plurality of regions of each of said substrates.

Claim 97 (New): The method of claim 89, wherein said step of adjusting comprises activating actuators each configured to impart a selected one of a push force or a pull force to one of said substrates.

Claim 98 (New): The method of claim 89, wherein a plurality of said actuators impart said forces upon one substrate.

Claim 99 (New): The method of claim 98, wherein at least one of said plurality of actuators is configured to impart a selected one of a push or a pull force to said one substrate, and at least another of said plurality of actuators is configured to impart only a push force to said one substrate.

Claim 100 (New): The method of claim 89, wherein each said plurality of probes disposed on each said substrate comprises an array of probes.

Claim 101 (New): The method of claim 89, wherein each said probe of one of said plurality of probes disposed on one of said substrates is elongate and resilient, whereby each said probe of said one of said plurality of probes provides individual compliance with respect to said terminals of said electronic device and said step of adjusting provides global planarization of said one of said plurality of probes with respect to said terminals of said electronic device.